

N-Ch 500V Fast Switching MOSFETs

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced VD MOSFETS

Product Summary



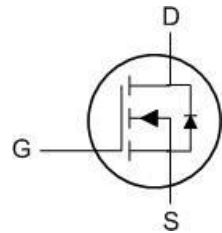
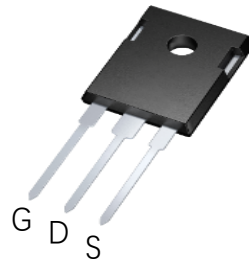
BVDSS	R _{DS(on)}	I _D
500V	0.23Ω	25A

Description

The XRT25N50HS is the Advanced VD N-ch MOSFETS, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications.

The XRT25N50HS meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

TO247 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	500	V
V _{GS}	Gate-Source Voltage	±30	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	25	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	16	A
I _{DM}	Pulsed Drain Current ²	100	A
EAS	Single Pulse Avalanche Energy ³	866	mJ
I _{AS}	Avalanche Current	---	A
P _D @T _C =25°C	Total Power Dissipation ⁴	33	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	50	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	3.8	°C/W

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	500	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	---	---	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=12.5A$	---	0.23	0.30	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	3	4	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=500V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=500V, V_{GS}=0V, T_J=150^\circ\text{C}$	---	---	---	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=20V, I_D=21.5A$	---	---	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	---	---	Ω
Q_g	Total Gate Charge	$V_{DS}=250V, V_{GS}=0\text{ to }10V, I_D=25A$	---	69	---	nC
Q_{gs}	Gate-Source Charge		---	19.2	---	
Q_{gd}	Gate-Drain Charge		---	21.8	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{GS}=10V, V_{DS}=250V, R_G=24\Omega, I_D=25A$	---	48	---	ns
T_r	Rise Time		---	68	---	
$T_{d(off)}$	Turn-Off Delay Time		---	197	---	
T_f	Fall Time		---	79	---	
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	---	3415	---	pF
C_{oss}	Output Capacitance		---	305	---	
C_{rss}	Reverse Transfer Capacitance		---	32	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	25	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=25A, T_J=25^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=25, di/dt=100A/\mu s,$	---	475	---	nS
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	6.8	---	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J=25^\circ\text{C}$, $V_{DD}=50V, V_G=10V, R_G=25\Omega, L=10\text{mH}, I_{AS}=13A$
 3. $R_{\theta JA}$ is measured with the device mounted on a minimum recommended pad of 2oz copper FR4 PCB
 4. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Output Characteristics

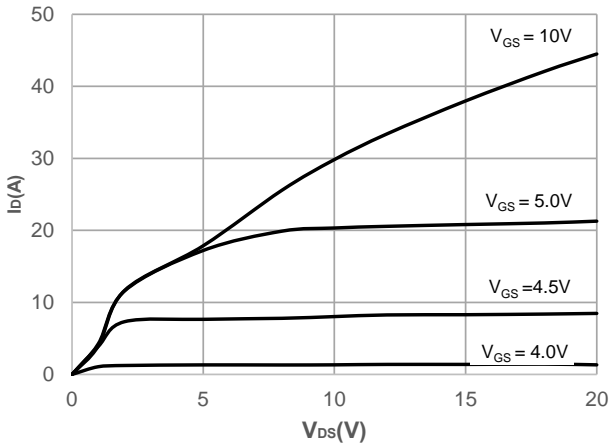


Figure 2: Typical Transfer Characteristics

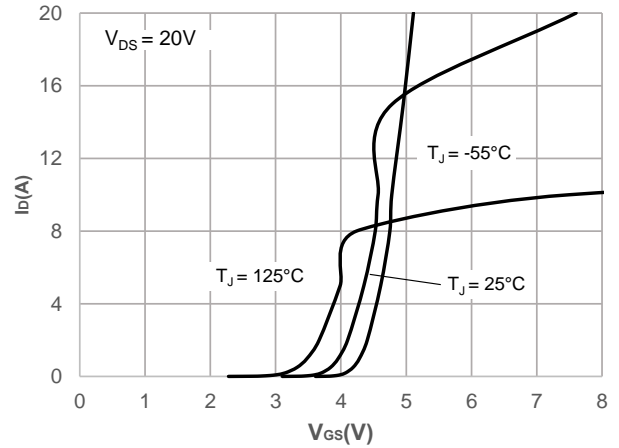


Figure 3: On-resistance vs. Drain Current

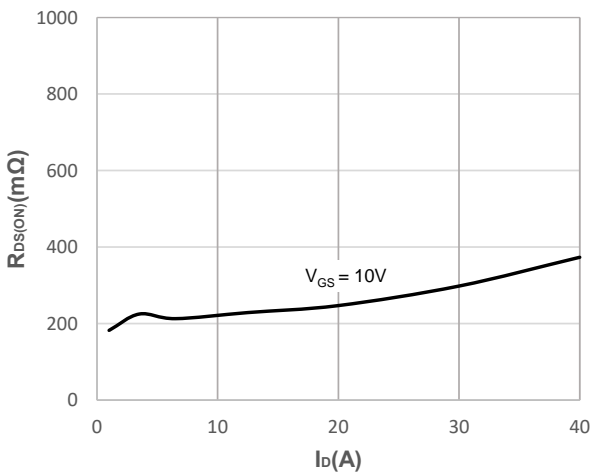


Figure 4: Body Diode Characteristics

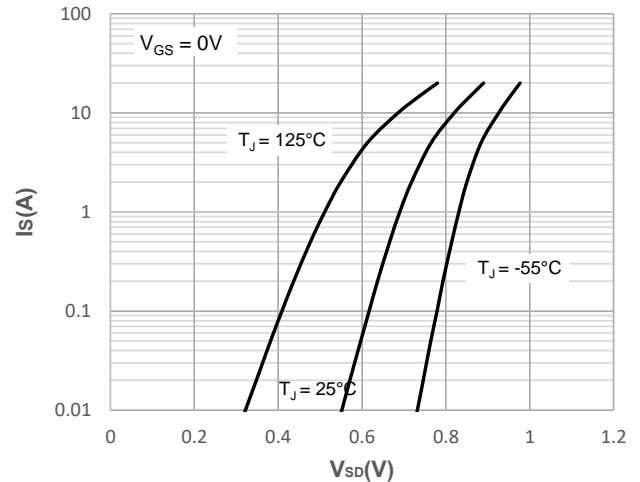


Figure 5: Gate Charge Characteristics

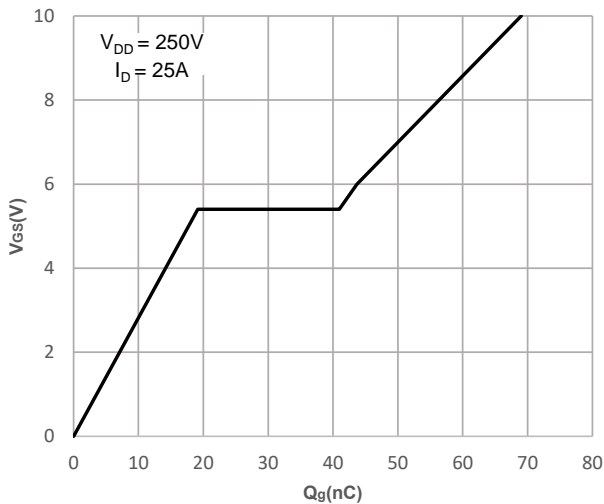
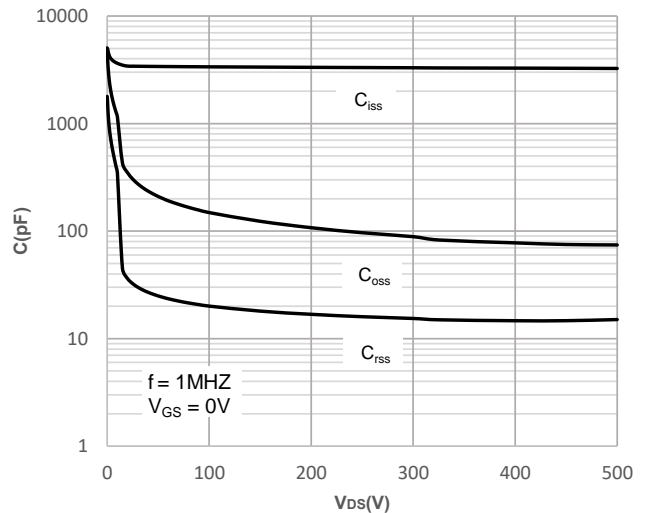


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

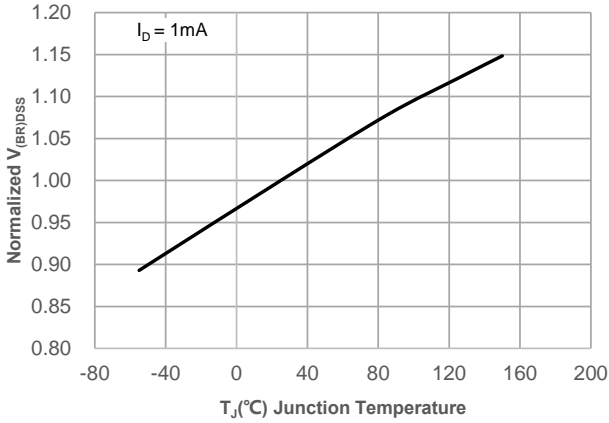


Figure 8: Normalized on Resistance vs. Junction Temperature

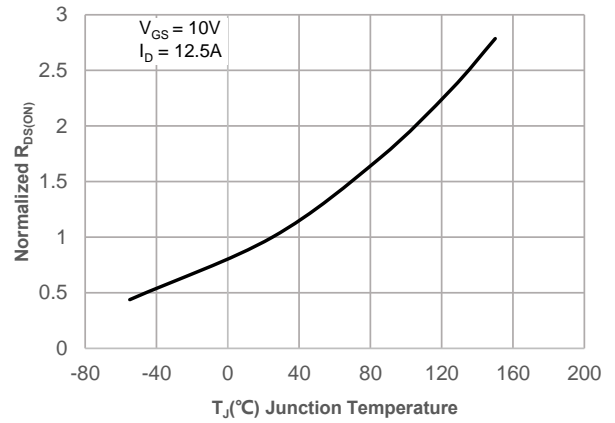


Figure 9: Maximum Safe Operating Area

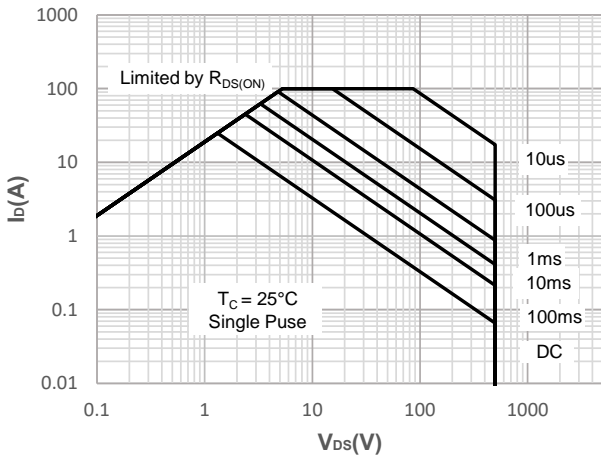


Figure 10: Maximum Continuous Driant Current vs. Case Temperature

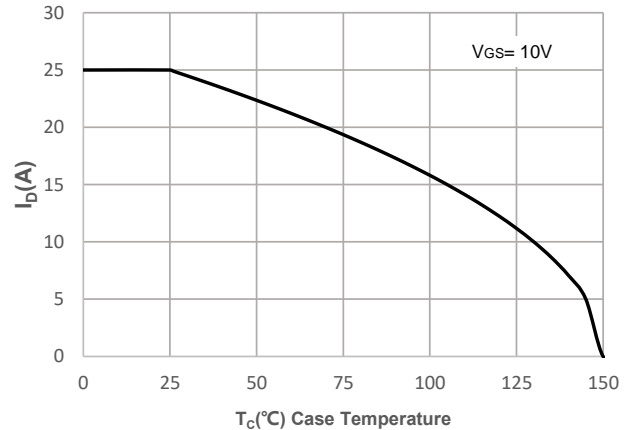


Figure 11: Normalized Maximum Transient Thermal Impedance

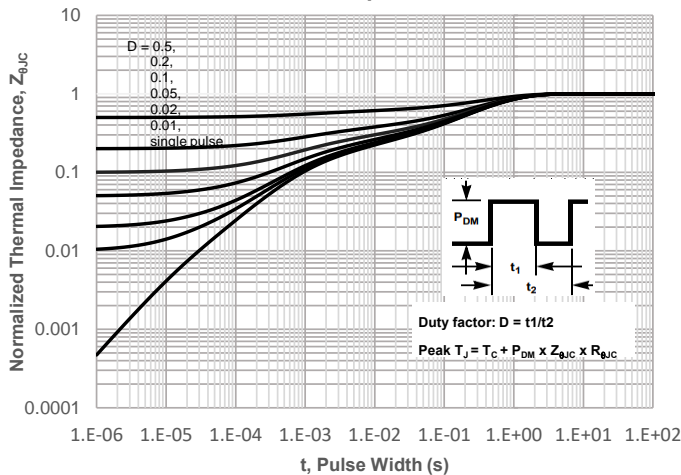
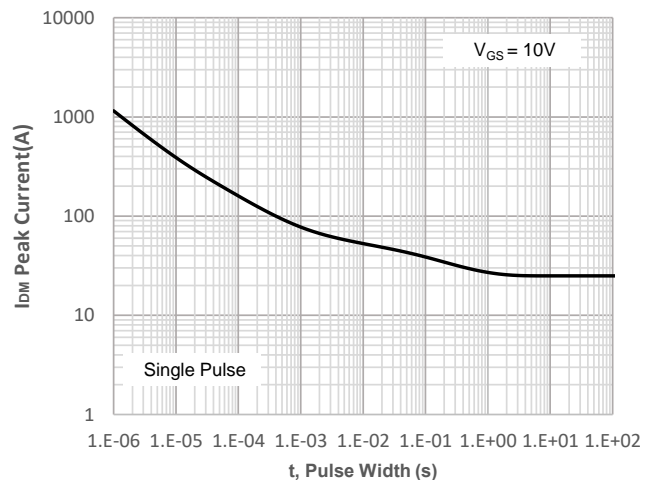
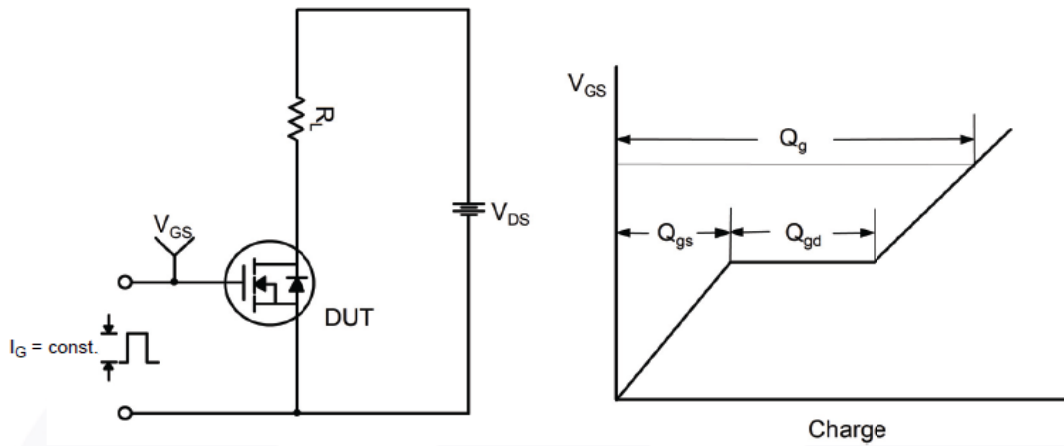


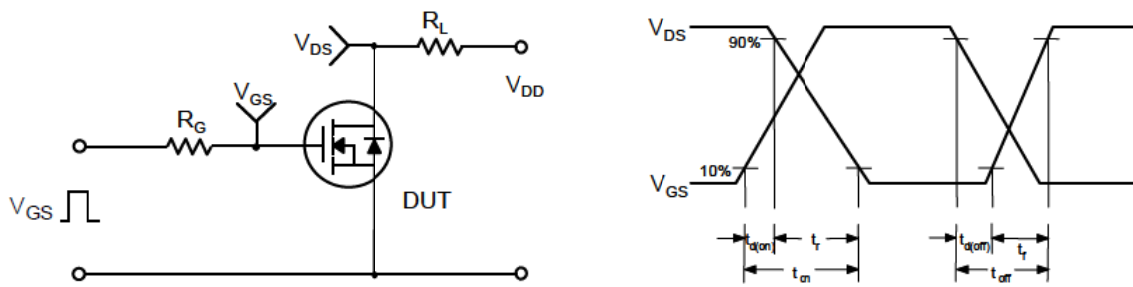
Figure 12: Peak Current Capacity



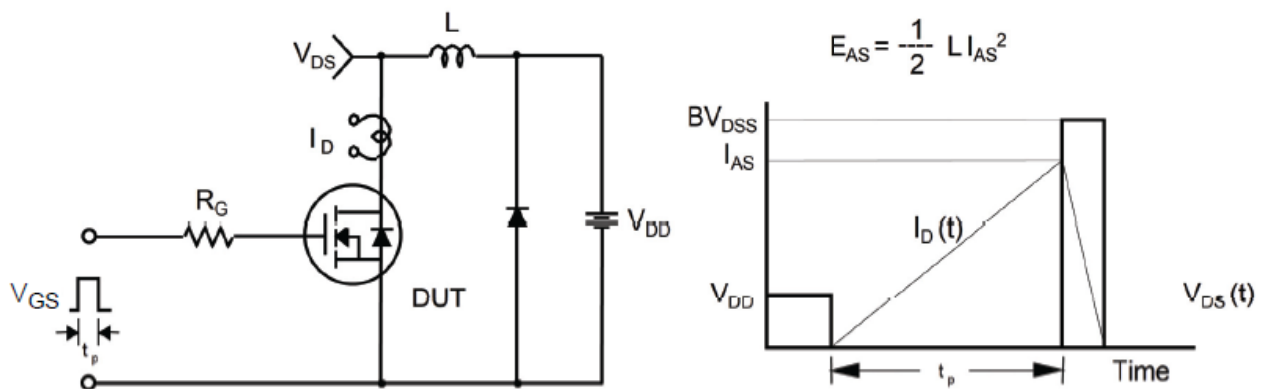
Gate Charge Test Circuit & Waveform



Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions for TO247S

